



# SynPower — Co-Create to make better!

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# Outline

I. Company Profile

II. Operational Overview

III. Outlook and Strategy

## Main Operating Locations

- ◆ Taiwan Operating Location: Taoyuan District

Mainland Operating Locations: Kunshan, Dongguan, Huai'an, Qinhuangdao

Overseas Operating Locations: Bangkok, Thailand; Chennai, India

## Close to Demand, Localized Service

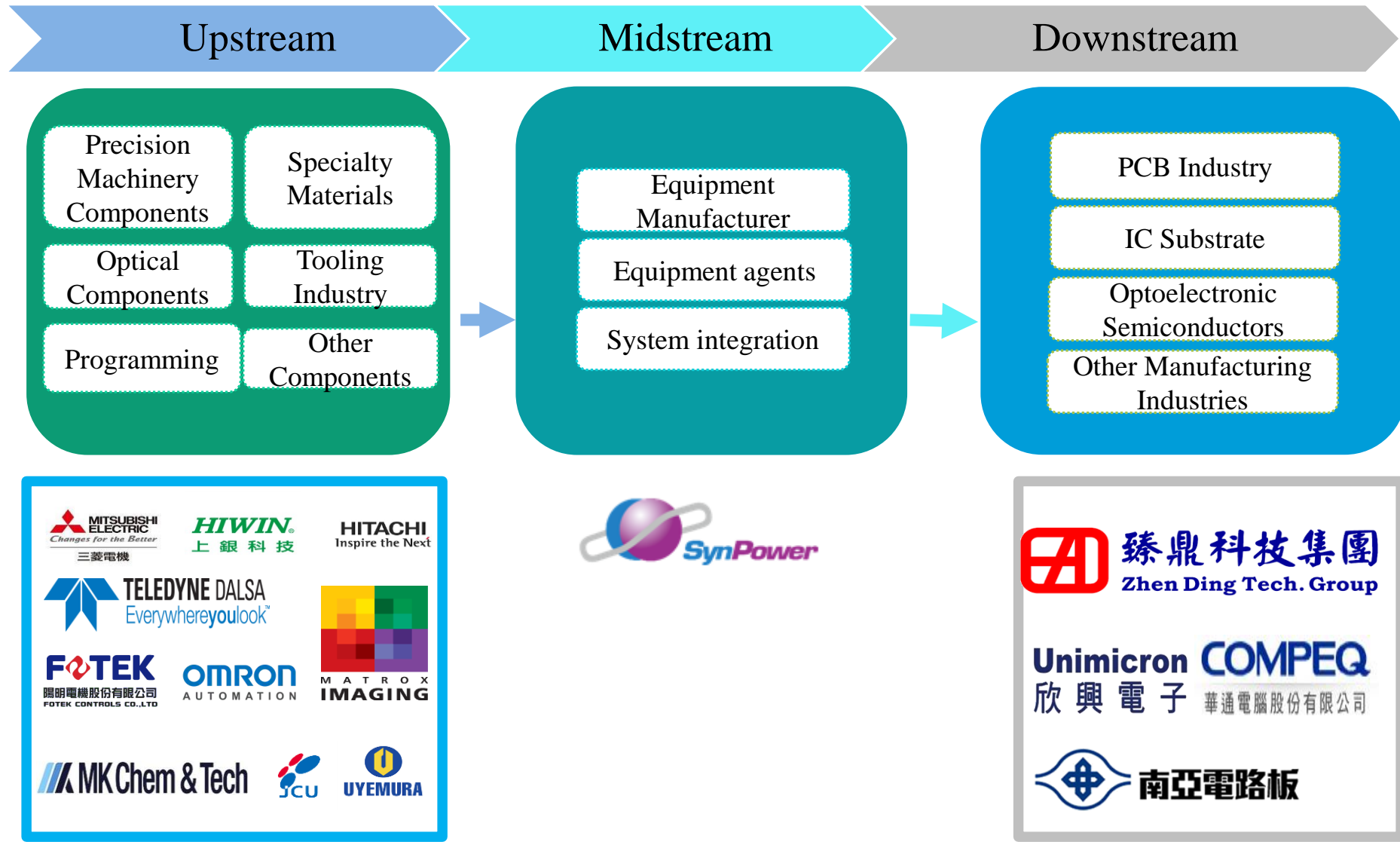


- ◆ Established : May, 2002
  - ◆ Capital Amount : NT\$ 329 million
  - ◆ Number of Employees: Approximately 300
- Committed to automation equipment and machine vision application business in industries such as circuit boards and semiconductors.
- Subsidiaries :
    - SynTop : Various horizontal wet process equipment
    - Chipboard Technology : PCB surface treatment OEM



# ➤ Industry Position (Relationships within the Industry's Upstream, Midstream, and Downstream)

## I. Company Profile

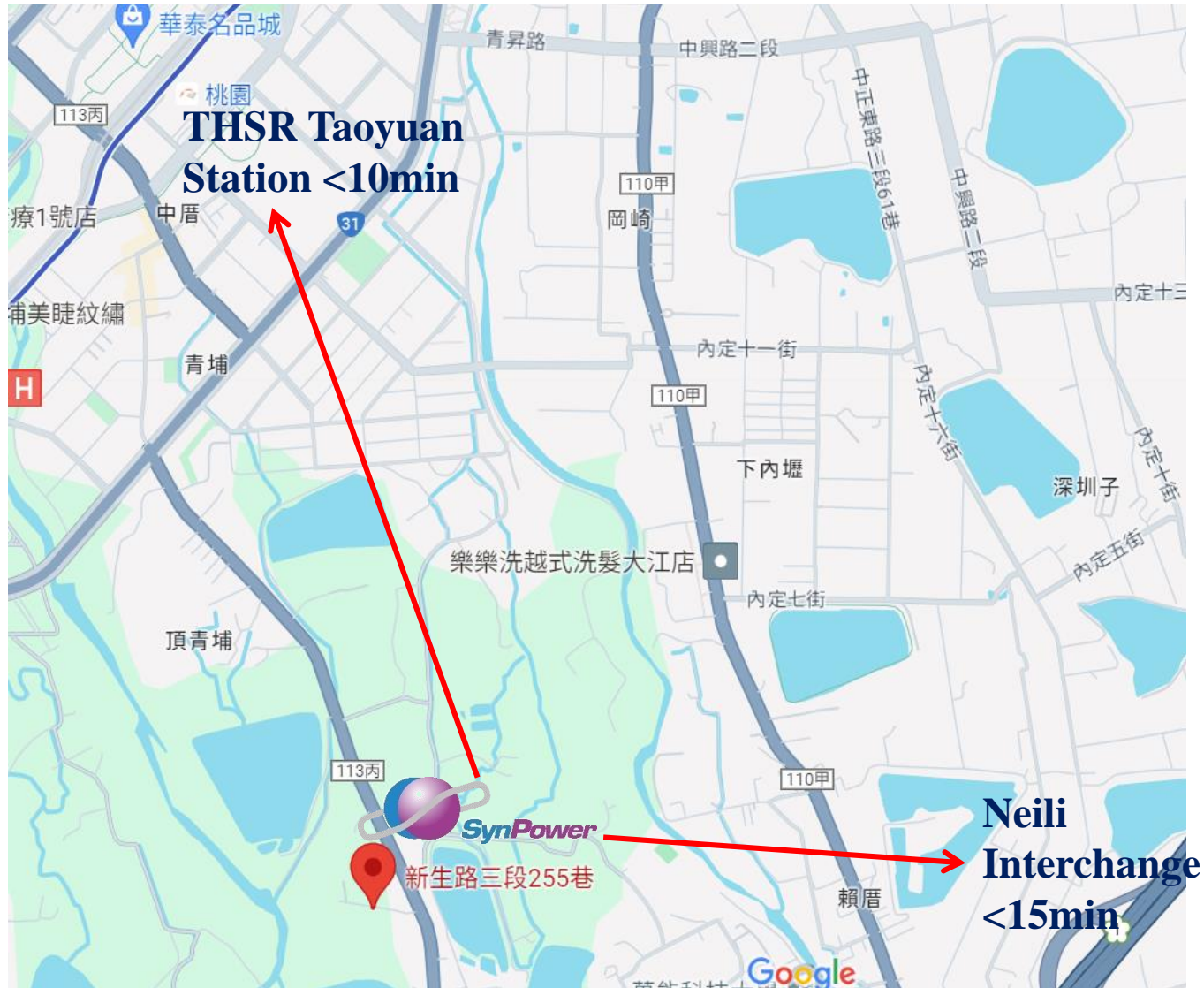




# ➤ The New Factory under construction in Qingpu

## I. Company Profile

**Location : Lane 255, Section 3, Xinsheng Road**



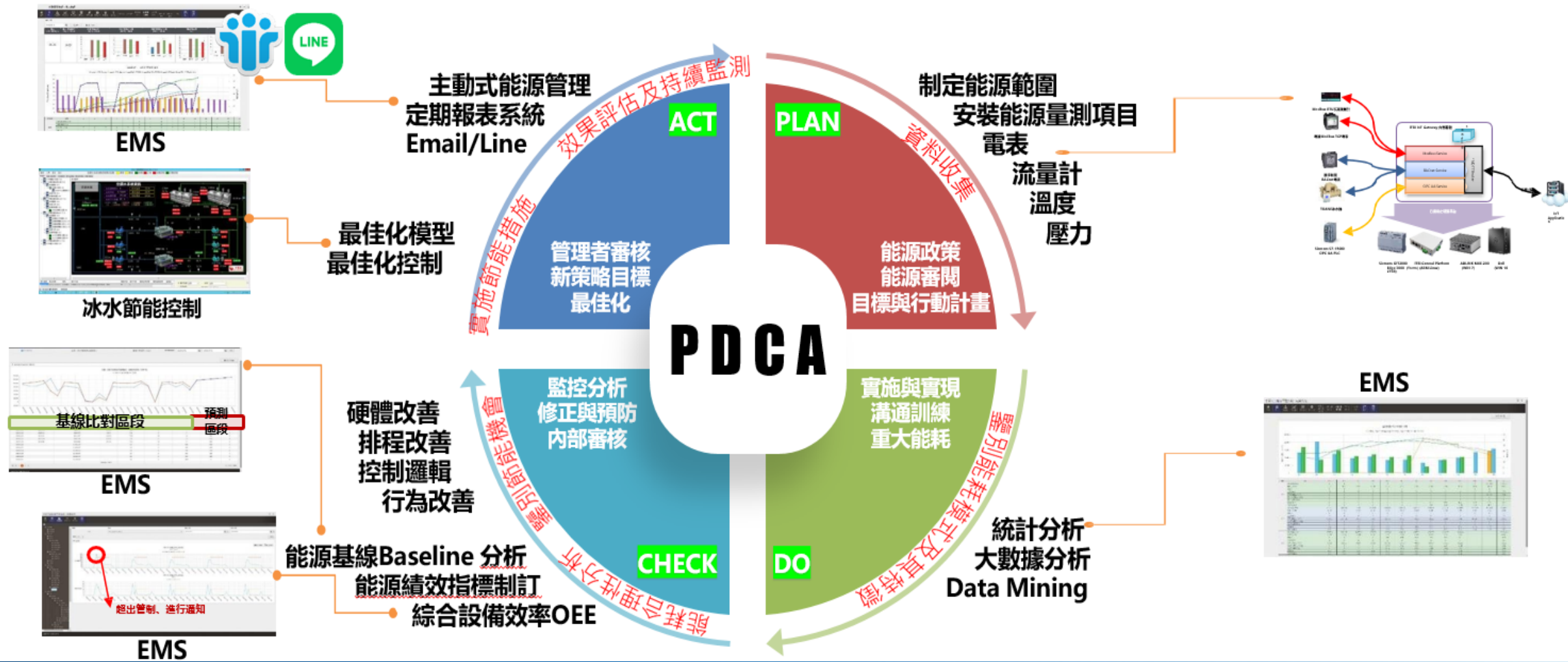
- ◆ Expected to be operational in August 2025
- ◆ Floor Area (including Basement Level 1) : 3,600 Pin
- ◆ New Factory Exterior Renderings:



➤ Net Zero Carbon Emissions Policy Target, with Gradual Implementation of Carbon Reduction Measures by 2050

I. Company Profile

Establish energy management system





## I. Company Profile

Ruth Society For Disability Services Bade Spring Fair on March 23, 2024



Raise funds for children's meals in Ruth Society on November 25, 2024.



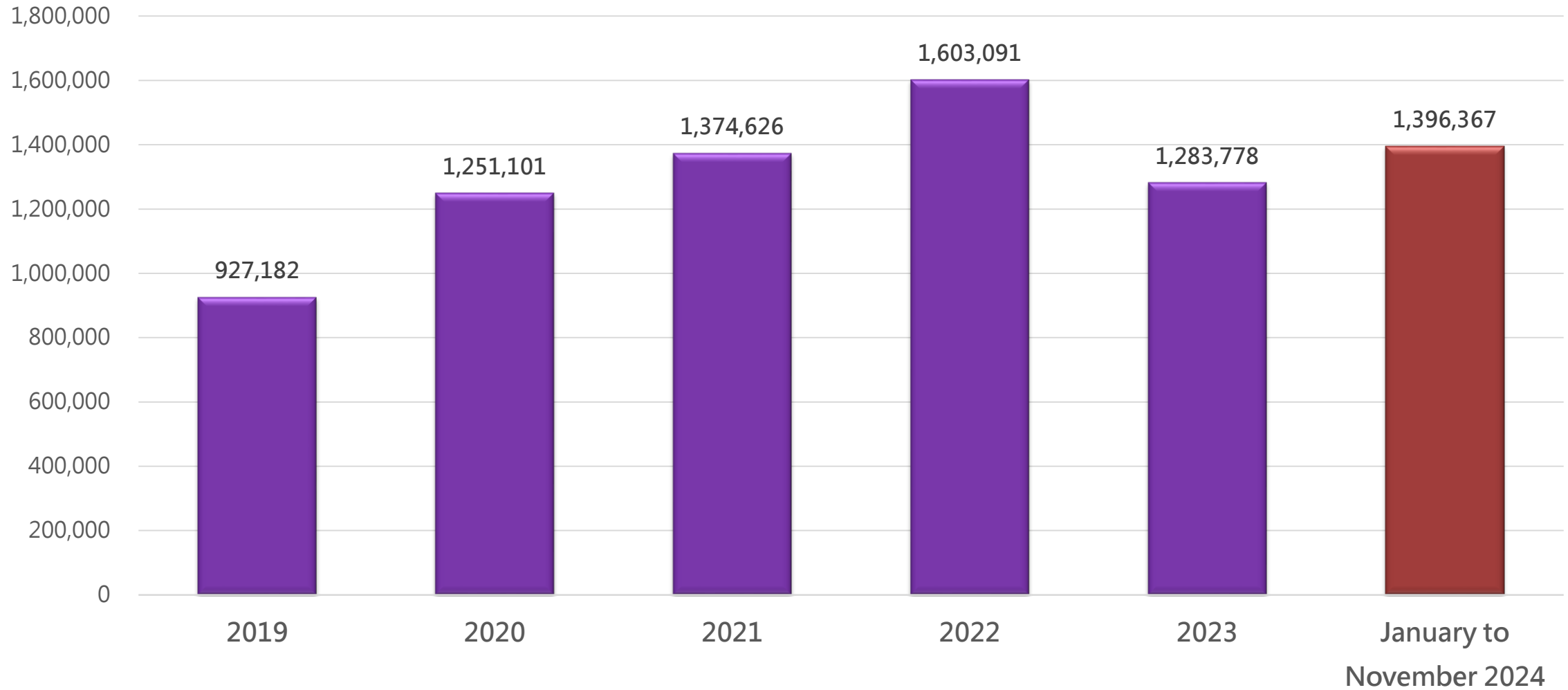
Chinese Fund for Children and Families - Slow Learners "Slow Fly" Event on November 11, 2023





## II. Operational Overview

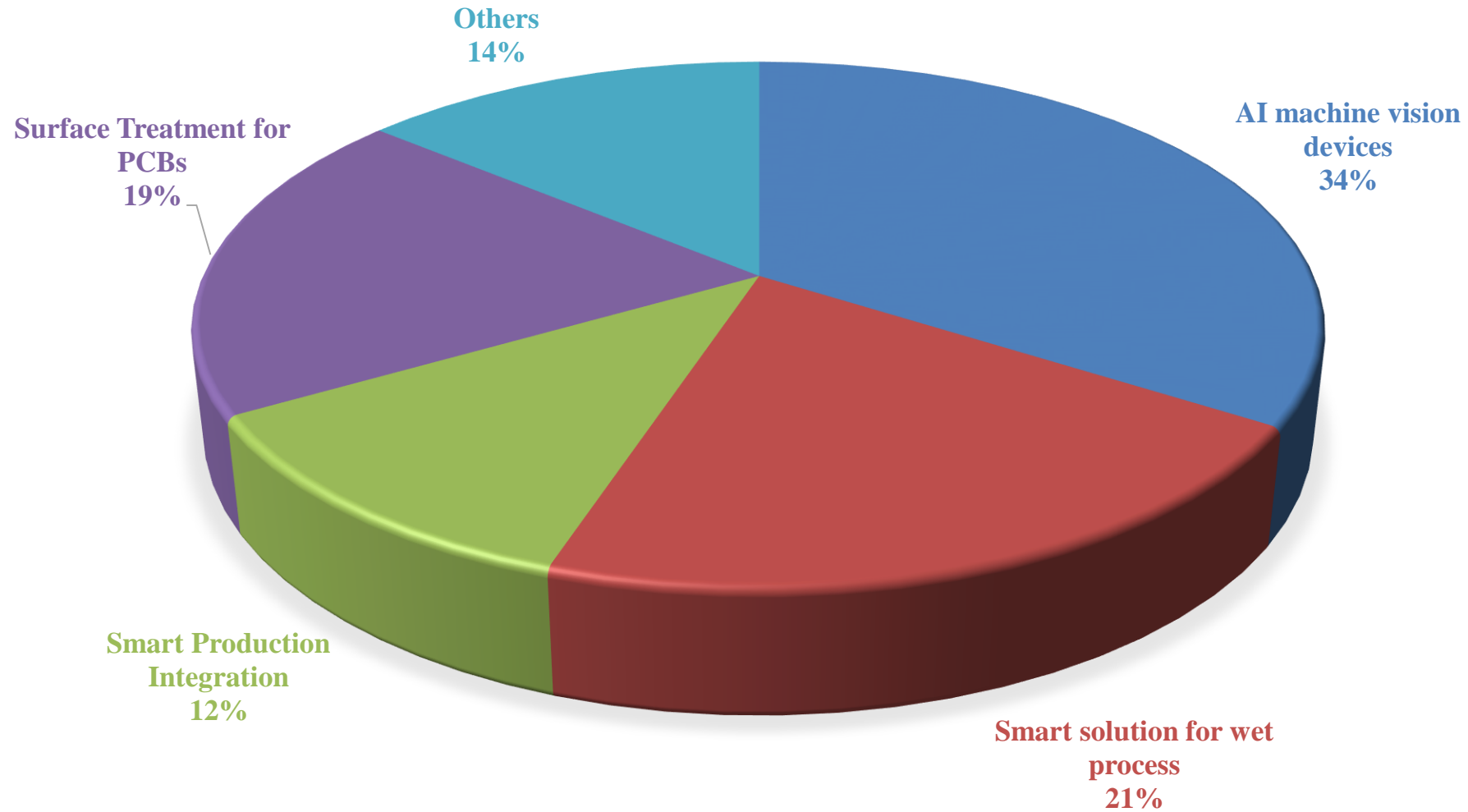
### Annual Revenue (NT\$ thousand)



## ➤ Sales Performance - Performance Report

### II. Operational Overview

#### Main sales product categories from Jan to Nov in 2024



## ➤ Dividend Policy

Adhering to a stable dividend policy, the dividend distribution over the past 5 years is as follows:

Unit : NT\$

Year		2019	2020	2021	2022	2023
Dividend Policy	Cash	1.2	0.6	1.2	2	1.2
	Stock	-	1.2	-	-	-
Total		1.2	1.8	1.2	2	1.2

The company is in a growth stage, and in order to meet the needs for capital expenditure, business expansion, and financial planning for sustainable development, our dividend distribution policy focuses on a balance between cash dividends and stock dividends. **The cash dividend payout ratio will not be less than 10% of the total dividend distribution based on the current year's earnings.** This will be determined by factors such as the company's current and future investment environment, capital requirements, economic conditions, and industry changes. The policy also takes into account shareholders' interests, balances dividends, and supports the company's long-term financial planning. Each year, the board of directors will propose an earnings distribution plan, which will be subject to approval by the shareholders' meeting.



# 1. SynPower

01

A subsidiary has been established in Thailand, and orders for optical measurement and wet process equipment have been received.

02

Continuing the promotion of high-end mobile phone module appearance inspection equipment.

03

Online systems and energy-saving waste reduction solutions.

04

AI to reduce inspection misjudgments and AI inspection logic applied to industries beyond PCBs.

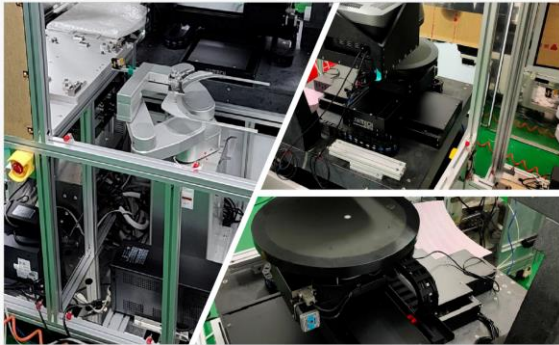
05

Collaborating with Japan to develop the external inspection machine with the best detection capabilities.

06

Preparing the development plan for AOI automated inspection in semiconductor packaging and testing processes.

### III. Outlook and Strategy



The automated integration solution jointly launched by Keyence and SynPower is aimed at the semiconductor wafer packaging and testing industry that requires high yield and relies on excellent precision equipment.

SynPower 's automated integration solution significantly shortens the measurement time of each piece from 25 minutes for manual measurement to 5 minutes. It can upgrade batch sampling inspection to full inspection, improving the yield rate of tanking operations and reducing waste in the subsequent process.

### 2. SynTop



Order for wet process equipment obtained from a new factory built by a Thai customer.

Energy-saving fans have been introduced to major customers and are being tested in other plants.

The installation of the glass substrate electroplating demo equipment is underway.



➤ Integrating materials and equipment to provide a complete TGV solution.

## Glass Substrate TGV Process and Equipment



### High Aspect Ratio Laser-Enhanced Deep Etching

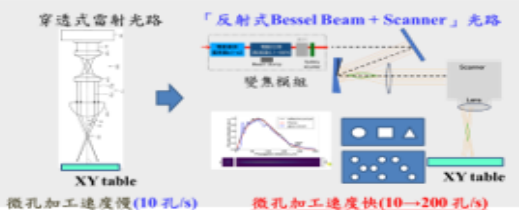
**Legend Laser**

Processing Speed

- Array Holes: 5000 hole/s
- Non Array Holes: 200 hole/s

KOH Etching Equipment

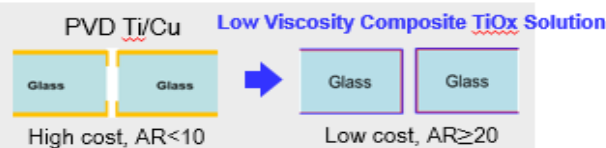
- Hole Diameter Uniformity: >90%



### Development of High Aspect Ratio Glass Adhesion Layers

**SynPower**

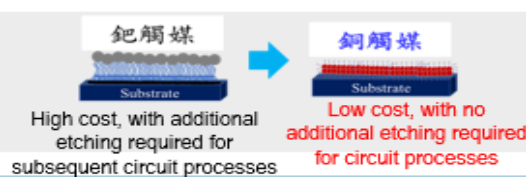
- Adhesion Layer Thickness: 100~200 nm
- Adhesion Strength:  $\geq 5$  N/cm
- Step Coverage:  $\geq 65\%$
- Fully Wet Coating Equipment



### High Aspect Ratio Glass Seed Layer Copper Catalyst & High-Filling Chemical Copper Solution

**Chinte Technology**

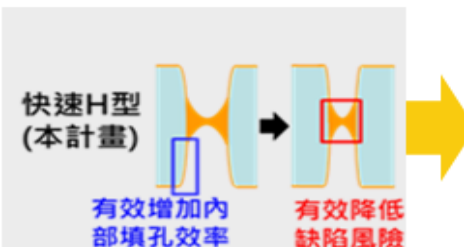
- Seed Layer Thickness:  $\geq 250$  nm
- Catalyst Adsorption:  $\leq 0.2$  mg/dm<sup>2</sup>
- Step Coverage:  $\geq 70\%$
- Adhesion: ASTM 5B @ 8 inches
- Fully Wet Chemical Deposition Equipment



### High Aspect Ratio Glass Metallization and Via Filling Electroplating

**SynPower**

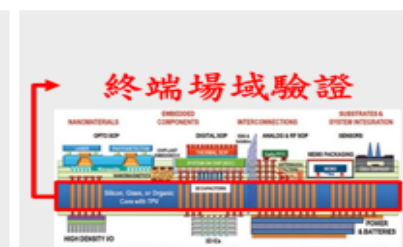
- Via Filling Yield:  $\geq 95\%$
- Bridging Time:  $\leq 1$  hour
- Copper Thickness:  $\leq 15$   $\mu$ m
- Fully Wet High Aspect Ratio Electroplating Equipment



### TGV Substrate Patterning and Reliability Testing

**Ecocera Optronics**

- Adhesion Layer Removal
- RDL (Redistribution Layer) Circuit Fabrication
- 6 Types of Substrate Reliability Verification Tests



## III. Outlook and Strategy

### 3. Chipboard Technology



The thin nickel process foundry line for high-frequency applications will begin taking orders in 2025.

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Thank you for your guidance.